WHAT IS CLAIMED IS:

1. A wiring board used for an electro-optical device that includes an electro-optical element and a driver circuit to drive the electro-optical element, the wiring board comprising:

a feed line film to supply the driver circuit with current to put the electro-optical element into operation;

a signal line film to supply the driver circuit with a level signal to determine intensity of the current to be supplied to the electro-optical element; and

an operation line film to supply the driver circuit with an operation instruction signal to instruct whether to put the electro-optical element into operation;

the feed line film constituting an upper layer among the feed line film, the signal line film, and the operation line film.

2. The wiring board according to claim 1, the feed line film being thicker than at least one of the signal line film and the operation line film.

3. The wiring board according to claim 1, the feed line film being a conductive film having lower resistance than at least one of the signal line film and the operation line film.

4. The wiring board according to claim 1, the feed line film and the operation line film being disposed in the same layer.

5. The wiring board according to claim 1, the operation line film and the feed line film being formed to extend substantially parallel to each other.

6. The wiring board used for an electro-optical device that includes a display region and a driver circuit, the display region including a plurality of basic pixels, each including at least one electro-optical element, the driver circuit driving each of the at least one electro-optical element, the wiring board comprising:

a plurality of feed line films to supply the driver circuit with current to put the electro-optical element into operation;

a plurality of signal line films to supply the driver circuit with a level signal to determine intensity of the current to be supplied to the electro-optical element; and

a plurality of operation line films to supply the driver circuit with an operation instruction signal to instruct whether to put the electro-optical element into operation;

the feed line films constituting an upper layer among the feed line films, the signal line films, and the operation line films; and

the plurality of feed line films being disposed along the array of the basic pixels, and at least one feed line film being shared by two adjacent columns of the basic pixels.

7. The wiring board according to claim 6, each of the basic pixels including three electro-optical elements, and the feed line films being disposed so that three of the plurality of feed line films are shared by two adjacent columns of the basic pixels.

8. The wiring board according to claim 6, the feed line films, the operation line films, and the signal line films being arranged in reflection symmetry along the center line that is the boundary between two adjacent columns of the basic pixels.

9. A circuit board used for an electro-optical device that includes an electro-optical element and a driver circuit to drive the electro-optical element, the circuit board comprising:

a circuit thin film holding the driver circuit;

a feed line film to supply the driver circuit with current to put the electro-optical element into operation;

a signal line film to supply the driver circuit with a level signal to determine intensity of the current to be supplied to the electro-optical element; and

an operation line film to supply the driver circuit with an operation instruction signal to instruct whether to put the electro-optical element into operation;

the feed line film constituting an upper layer among the circuit thin film, the feed line film, the signal line film, and the operation line film.

10. The circuit board according to claim 9, the driver circuit including a plurality of thin film transistors, one of the signal line film and the operation line film and gate lines of the thin film transistors being disposed in the same layer, and the other of the signal line film and the operation line film and source/drain lines of the thin film transistors being disposed above the layer.

11. An electro-optical device, comprising:

the wiring board according to claim 1;

an electro-optical element; and

a driver circuit formed on the wiring board.

12. The electro-optical device according to claim 11, the driver circuit being a transferable circuit thin film formed on a transferor substrate different from the wiring board, and the driver circuit being separated from the transferor substrate and transferred to be

connected electrically with each of the feed line film, the signal line film, and the operation line film of the wiring board.

13. An electro-optical device, comprising:

the circuit board according to claim 9; and

an electro-optical element formed on the circuit board.

14. A method for manufacturing an electro-optical device that includes a display region and a driver circuit, the display region including a plurality of basic pixels, each including at least one electro-optical element, the driver circuit driving each of the electro-optical element, the method comprising:

forming a laminated wiring that includes a feed line film to supply the driver circuit with current to put the electro-optical element into operation, a signal line film to supply the driver circuit with a level signal to determine intensity of the current to be supplied to the electro-optical element, and an operation line film to supply the driver circuit with an operation instruction signal to instruct whether to put the electro-optical element into operation, on a first substrate according to the array of the basic pixels;

transferably forming a circuit thin film holding the driver circuit on a second substrate; and

transferring the circuit thin film from the second substrate to each region corresponding to the basic pixels on the first substrate, and connecting the circuit thin film with the laminated wiring;

the forming including forming the laminated wiring so that the feed line film constitutes an upper layer among the feed line film, the signal line film, and the operation line film.

15. The method for manufacturing an electro-optical device according to claim 14, the transferably forming including forming a delamination layer locating between the second substrate and the circuit thin film and having properties causing a change in state by the application of energy and reducing bonding strength with the circuit thin film.

16. A method for manufacturing an electro-optical device that includes an electro-optical element and a driver circuit to drive the electro-optical element, the method comprising:

forming, on a substrate, a circuit thin film holding the driver circuit, a feed line film to supply the driver circuit with current to put the electro-optical element into operation, a signal line film to supply the driver circuit with a level signal to determine intensity of the current to be supplied to the electro-optical element, and an operation line film to supply the

driver circuit with an operation instruction signal to instruct whether to put the electro-optical element into operation; and

forming the electro-optical element on the substrate on which the circuit thin film, the feed line film, the signal line film, and the operation line film are formed;

the forming the circuit thin film including forming each film so that the feed line film constitutes an upper layer among the circuit thin film, the feed line film, the signal line film, and the operation line film.

17. The method for manufacturing an electro-optical device according to claim 16, the driver circuit including a thin film transistor, one of the signal line film and the operation line film and a gate line of the thin film transistor being disposed in the same layer, and the other of the signal line film and the operation line film and a source/drain line of the thin film transistor being disposed above the layer.

18. An electronic device, comprising:

the electro-optical device according to claim 11 usable as a display.